

Capacitor Materials

ET1801



Lead Free Solderable End Termination

Description:

ET1801 is a Pb and Cd free solderable Ag/Pd/Pt end termination designed for use on MLCC (multilayer ceramic chip capacitors). It offers excellent solderability and leach resistance.

● Key Benefits :

- Lead and Cadmium free
- Suitable rheology for machine dip application
- Excellent Solderability and leach resistance
- Compatible on titanate ceramic bodies

● Typical Properties:

Viscosity :

30-40 Kcps, Brookfield RVT,
SC4-14 spindle and 6R cup at 10 RPM and 25°C.

Solids :

79.25 ± 1.0%

Solderability :

60Sn/40Pb @ 245°C
5 sec dip, RMA Flux
≥ 95% Solder Coverage

Solder Leaching :

60Sn/40Pb @ 245°C
20 sec dip, RMA Flux
≥ 95% Solder Coverage

● Recommended Processing Guidelines:

Drying :

180°C peak drying profile
10 minutes at peak temperature
20 minute total cycle time

Firing Profile :

Fire at 780-810°C
Dwell time of 5-6 minutes

Thinner :

RV-372 (Terpineol)

Warranty:

Material guaranteed to meet specifications for 6 months from date of shipment.

Storage :

Store in a dry location at 5-25°C.

DO NOT REFRIGERATE.

Allow paste to come to room temperature prior to opening.
Spatulate well before using.

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Americas
Heraeus Materials Technology LLC
Thick Film Materials Division
24 Union Hill Road
West Conshohocken, PA 19428
USA
Phone: +1 (610) 825-6050
E-Mail: techservice.hcd@heraeus.com
Internet: www.thickfilm.net

Europe
W.C. Heraeus GmbH
Thick Film Materials Division
Heraeusstr. 12-14
63450 Hanau
Germany
Phone: +49 (6181) 35-5466
E-mail: th-info@heraeus.com
Internet: www.heraeus-thickfilm.com

Asia
Heraeus Materials Technology
Shanghai Ltd.
No. 1 Guang Zhong Road
Zhuanqiao Town, Minhang District
Shanghai 201108
People's Republic of China
Phone: + 86 (21) 3357-5688
E-Mail: th.hmts@heraeus.com
Internet: www.heraeus-thickfilm.com